



Material Content Data Sheet



Sales Product Name		IR38165MTRPBF		Issued		24. January 2018		
MA#		MA001688596		Weight*		118.96 mg		
Package		PG-IQFN-34-900						
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.459	4.59	4.59	45886	45886
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		110	
	non noble metal	zinc	7440-66-6	0.052	0.04		438	
	non noble metal	iron	7439-89-6	1.043	0.88		8764	
wire	non noble metal	copper	7440-50-8	42.333	35.59	36.52	355861	365173
	noble metal	gold	7440-57-5	0.504	0.42	0.42	4239	4239
	encapsulation	organic material	carbon black	1333-86-4	0.102	0.09		860
encapsulation	plastics	epoxy resin	-	5.267	4.43		44276	
	inorganic material	silicondioxide	60676-86-0	45.768	38.47	42.99	384732	429868
	leadfinish	noble metal	palladium	7440-05-3	0.001	0.00		12
plating	noble metal	gold	7440-57-5	0.002	0.00		19	
	non noble metal	nickel	7440-02-0	0.041	0.03	0.03	343	374
	noble metal	palladium	7440-05-3	0.001	0.00		12	
solder	noble metal	gold	7440-57-5	0.002	0.00		19	
	non noble metal	nickel	7440-02-0	0.042	0.04		355	
	noble metal	silver	7440-22-4	0.604	0.51	0.55	5076	5462
heat sink CLIP	noble metal	silver	7440-22-4	0.149	0.13		1253	
	non noble metal	tin	7440-31-5	0.298	0.25		2507	
	non noble metal	lead	7439-92-1	5.517	4.64	5.02	46379	50139
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.004	0.00		30	
	non noble metal	zinc	7440-66-6	0.014	0.01		119	
	non noble metal	iron	7439-89-6	0.282	0.24		2373	
	non noble metal	copper	7440-50-8	11.460	9.63	9.88	96337	98859
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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